

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.18414	100.0	1.7
			<b>Subtotal</b>	<b>0.18414</b>	<b>100</b>	<b>1.7</b>
Post-plating	Tin solder	Bismuth (Bi)	7440-69-9	0	0.0	0
	Tin solder	Tin (Sn)	7440-31-5	0.79716	99.99	7.35926
	Tin solder	Copper (Cu)	7440-50-8	0	0.0	0
	Tin solder	Lead (Pb)	7439-92-1	0.00008	0.01	0.00074
	Tin solder	Antimony (Sb)	7440-36-0	0	0.0	0
	<b>Subtotal</b>	<b>0.79724</b>	<b>100</b>	<b>7.36</b>		
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.006	0.03	0.05543
	Copper alloy	Iron (Fe)	7439-89-6	0.02002	0.1	0.18478
	Copper alloy	Copper (Cu)	7440-50-8	19.93536	99.6	184.04088
	Pure metal layer	Silver (Ag)	7440-22-4	0.05404	0.27	0.49891
	<b>Subtotal</b>	<b>20.01542</b>	<b>100</b>	<b>184.78</b>		
Adhesive	Polymer	Paraffin wax	8002-74-2	0.09272	20.0	0.856
	Polymer	Epoxy resin system		0.03709	8.0	0.3424
	Filler	Silver (Ag)	7440-22-4	0.3338	72.0	3.0816
	<b>Subtotal</b>	<b>0.46361</b>	<b>100</b>	<b>4.28</b>		
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	0.7134	2.5	6.586
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.14019	7.5	19.758
	Filler	Silica -amorphous-	7631-86-9	10.55828	37.0	97.4728
	Pigment	Carbon black	1333-86-4	0.14268	0.5	1.3172
	Polymer	Epoxy resin system		4.28038	15.0	39.516
	Filler	Silicon Dioxide (SiO2)	14808-60-7	10.55828	37.0	97.4728
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.14268	0.5	1.3172
	<b>Subtotal</b>	<b>28.53589</b>	<b>100</b>	<b>263.44</b>		
Wire	Copper alloy	Copper (Cu)	7440-50-8	0.0091	100.0	0.084
<b>Subtotal</b>	<b>0.0091</b>	<b>100</b>	<b>0.084</b>			
Die	Doped silicon	Silicon (Si)	7440-21-3	0.17331	100.0	1.6
			<b>Subtotal</b>	<b>0.17331</b>	<b>100</b>	<b>1.6</b>
Post-plating	Tin solder	Bismuth (Bi)	7440-69-9	0	0.0	0
	Tin solder	Tin (Sn)	7440-31-5	0.79716	99.99	7.35926
	Tin solder	Copper (Cu)	7440-50-8	0	0.0	0
	Tin solder	Lead (Pb)	7439-92-1	0.00008	0.01	0.00074
	Tin solder	Antimony (Sb)	7440-36-0	0	0.0	0
	<b>Subtotal</b>	<b>0.79724</b>	<b>100</b>	<b>7.36</b>		
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.006	0.03	0.05543
	Copper alloy	Iron (Fe)	7439-89-6	0.02002	0.1	0.18478
	Copper alloy	Copper (Cu)	7440-50-8	19.93536	99.6	184.04088
	Pure metal layer	Silver (Ag)	7440-22-4	0.05404	0.27	0.49891
	<b>Subtotal</b>	<b>20.01542</b>	<b>100</b>	<b>184.78</b>		
Adhesive	Polymer	Paraffin wax	8002-74-2	0.09272	20.0	0.856
	Polymer	Epoxy resin system		0.03709	8.0	0.3424
	Filler	Silver (Ag)	7440-22-4	0.3338	72.0	3.0816
	<b>Subtotal</b>	<b>0.46361</b>	<b>100</b>	<b>4.28</b>		
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	0.7134	2.5	6.586
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.14019	7.5	19.758
	Filler	Silica -amorphous-	7631-86-9	10.55828	37.0	97.4728
	Pigment	Carbon black	1333-86-4	0.14268	0.5	1.3172
	Polymer	Epoxy resin system		4.28038	15.0	39.516
	Filler	Silicon Dioxide (SiO2)	14808-60-7	10.55828	37.0	97.4728
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.14268	0.5	1.3172
	<b>Subtotal</b>	<b>28.53589</b>	<b>100</b>	<b>263.44</b>		
Wire	Copper alloy	Copper (Cu)	7440-50-8	0.0091	100.0	0.084
<b>Subtotal</b>	<b>0.0091</b>	<b>100</b>	<b>0.084</b>			
<b>Total</b>				<b>99.99997</b>	<b>100</b>	<b>923.188</b>

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